substrate 21, solder balls for connecting the CSP to external circuits, and package mold resin 24 enclosing the CSP. The CSP 222 shown in FIG. 2B has a structure similar to that of FIG. 2A except that ball bumps 26 instead of wires are used to connect the bare die 22 to the substrate 21. According to this invention, a bare die 22 is embedded and packaged above a CSP substrate 21 within a conventional CSP, and the conventional CSP is embedded and disposed above an MCM substrate 31 within an MCM package structure as shown in FIGs. 3A-3F.

CLAIMS:

Amend claims 41 and 49 as follows:

41. (Twice Amended) A multi-chip module package structure comprising:

a multi-chip module substrate;

at least two chip packages, each of said chip packages being a packaged chip module having a bare chip and a chip substrate packaged and enclosed therein, said at least two chip packages having been burn-in tested and function tested;

a plurality of electrical connect points electrically connecting said chip packages with said multi-chip module substrate;

a plurality of electrical connect pins; and

a package material enclosing said multi-chip module substrate, said connect points and said chip packages.

49. (Twice Amended) A multi-chip module package structure comprising:

a multi-chip module substrate;

at least a bare chip;

at least one chip package being a packaged chip module having a bare chip and a chip substrate packaged and enclosed therein, said at least one chip package having been burn-in tested and function tested;

a plurality of electrical connect points electrically connecting said bare chip and said at least one chip package with said multi-chip module substrate;

a plurality of electrical connect pins; and

a package material enclosing said multi-chip module substrate, said connect points, said bare chip and said at least one chip package.